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TABLE OF CONTENTS

Underfill with High Thermal Conductivity in Silicon Photonic Chiplets for Co-Packaged Optics (CPO) Devices	1
<i>Dai-Fei Li, Wen-Yu Teng, Liang-Yih Hung, Andrew Kang, Yu-Po Wang, Don-Son Jiang</i>	
Packaging Technology for Ion Trap Quantum Processor Chips	5
<i>Nila Krishnakumar, Friederike Giebel, Eike Iseke, Konstantin Thronberens, Jacob Stupp, Nora D. Stahr, Christian Ospelkaus</i>	
Automated 5-Axis System for Mosquito Dispensed Waveguides	7
<i>Laura Fütterer, Andreas Evertz, Ludger Overmeyer</i>	
Steeplly Bent Core Single-Mode Polymer Waveguide with Low Bending Loss Fabricated Using the Mosquito Method	9
<i>Ayu Tanimoto, Takaaki Ishigure</i>	
Development of Simultaneous Electrical and Optical Mounting for Co-Packaged Optics Modules	11
<i>Hisaaki Nishimura, Mizuki Tonomura, Misa Takahashi, Akari Watanabe, Megumi Oishi, Fumiaki Haraguchi, Tokuro Ozawa, Takeshi Yokoyama, Tomoyuki Akahoshi</i>	
Extremely Low Bending Loss (<0.5 dB at 1-mm Bending Radius) GI Core Polymer Optical Waveguide	15
<i>Masahiro Karakawa, Takaaki Ishigure</i>	
Chemical Resistant Dicing Tape for Hybrid Bonding Process	19
<i>Ryoh Takahashi, Koki Maruno, Kazutoshi Furuzono, Naoki Takahara, Seiji Kai</i>	
Inductors in Power Over Signal (PoC and PoDL) for in-Vehicle Networks	23
<i>Thomas Schamberger</i>	
Ultra-Small 145 GHz Coaxial Connector: Edge-Mount PCB Integration and Performance	27
<i>Hitoshi Onoduka, Yu-Cen Sun, Yushi Kirii</i>	
Effect of Thermal Distribution on Signal and Power Analysis of Large Complex 3D-IC System	31
<i>Yu Tomonaga, Tejas Jeurkar, Anushruti Jaiswal</i>	
Ultrathin Chips of III-V Bonding Process Using Laser Peel Transfer Technology for Co-Packaged Optics	35
<i>Haruka Fujishige, Takumi Ikehara, Tatsuya Okada, Yoshiyuki Arai, Jumpei Oniki, Daichi Miyazaki, Takenori Fujiwara, Yukari Jo</i>	
An 8-Channel MM VCSEL-Based Linear Drive CPO Transceiver for Compute and Backend Interconnects in AI/ML Systems	39
<i>Sho Yoneyama, Wataru Yoshida, Kazuya Nagashima, Kensho Nishizaki, Hideyuki Nasu</i>	
Chip-Scale Comb Lasers for Co-Packaged Optics	43
<i>Frank Smyth, M. Deseada Gutierrez, Shane Duggan, Alison Kearney, Chris McGuinness, Amol Delmade</i>	
New Optical Adhesive Design for CPO Packaging Solution	45
<i>Fumiya Suzuki, Masashi Kajiwar, Takashi Yamaguchi, Masayoshi Otomo, Noriyuki Sakai</i>	
High I/O Density Solution on Flip Chip Substrate for Advanced Package	49
<i>Yuan-Chang Ni, Hung Kun Chen, Yu Cheng Pai, Cheng Yu Kang, Jen Shang Chen, Wei Ching Chu, Yu-Po Wang, Don-Son Jiang</i>	

Development of Heat-Resistant UV-Curable Dicing Tape	53
<i>Reo Ozeki, Sayaka Tsuchiyama, Akio Fukumoto</i>	
Radiation-Induced Destructive Effects on COTS FPGA in GEO Satellite Environments	57
<i>Yuzo Yajima, Eisuke Haraguchi, Shigenori Tani, Hiroshi Kinoda, Hiroaki Miyake</i>	
Efficient Integral-Equation Methodology for Signal Integrity Analysis of Large-Scale IC Packages	61
<i>Hans Schreckenbach, Santosh Janaki Raman, Lucas Banting, Nima Chamanara, Andre Fecteau</i> <i>David Abraham, Max Hughson, Nick Geddert, Troy Lowry, Jonatan Aronsson</i>	
An Adjustable Energy-Recovering Electrical-Balance Duplexer for In-Band Full-Duplex Transceivers in the 6G FR3 Band	65
<i>Hsin-Chieh Lin, Chih-Hao Chuang, Yan-Qi Weng, Da-Chiang Chang, Hwann-Kaeo Chiou</i>	
Artifact Metrics and Individual Management of Semiconductor Packages	69
<i>Tsutomu Matsumoto</i>	
Digital-Twin-Driven Machine Learning for Thermal Optimization of Flip-Chip Packages	73
<i>Mohammad Rafiee, Vysak Vijayan Nair</i>	
Generation of the Thermal Digital Twin Model for an IC Chip	77
<i>Shuainan Lin, Yanbo Tang, Jiajia Sui, Chun-An Chi, Boping Wu, Cheng Yang, Harvey Jin, Fay Cui</i> <i>Jonny Wang</i>	
Extraction Techniques of Dielectric Characterization of Materials Up to E-Band Frequency	81
<i>Chia-Chu Lai, Ho-Chuan Lin, Vito Lin, Andrew Kang, Yu-Po Wang, Don-Son Jiang</i>	
Measurement and Analysis of Substrate Integrated Waveguide Using Low Temperature Co-Fired Ceramics at 250 GHz	85
<i>Nobuki Hiramatsu, Hiroshi Uchimura, Tuchjuta Ruckkwaen, Masahiro Tomisako, Kouhei Hirose</i> <i>Naoki Hirayama, Issei Watanabe, Kunio Sakakibara</i>	
Thermal Conductivity Aware Design Approach of Non-Conductive Film Layers for Enhanced Vertical Heat Dissipation in 3D HBM Packages	89
<i>Yuna Lee, Sang Won Yoon</i>	
A Novel Negative-Tone Chemically Amplified Photoresist of High Resolution and Chemical Resistance for Fine Copper Wirings	93
<i>Yuanfei Liu, Masahiko Ebihara, Irwansyah, Masahiro Miyasaka</i>	
Development of 1.6 μm Fine-Pitch RDL Damascene Process using Low-NA i-Line Stepper and a New Negative-Tone Photosensitive Dielectric Material	97
<i>Lili Wang, Murat Pak, Go Inoue, Kaho Shibasaki, Ayano Okuda, Kenyu Sugita, Nobuhiro Ishikawa</i> <i>Toshiyuki Ogata, Andy Miller, Eric Beyne</i>	
Study of Structural Evaluation in Fan-Out Large Body Size Packaging	101
<i>Liu Shuai-Lin, Shih Teny, Lin Vito, Lin Sam, Wang Yu-Po</i>	
Application of Graphene-Doped Polymer Optical Waveguides to Wavelength Convertor	105
<i>Ken Kuboyama, Naoki Yamaguchi, Sze Yum Set, Shinji Yamashita, Takaaki Ishigure</i>	
Low Wavelength Dependent Polymer Waveguide Type Multiplexer for MDM Link	109
<i>Takumi Kanai, Takaaki Ishigure</i>	

Miniaturization of 1×2 and 1×4 Branched Multimode Polymer Optical Waveguide for MUX Device in SWDM Links	113
<i>Koki Atsumi, Takaaki Ishigure</i>	
Development of a Rumen Bacteria Microbial Fuel Cell for Cattle Health and Methane Emission Monitoring Devices	117
<i>Michitaka Yamamoto, Jarred W. Fastier-Wooller, Shun Muramatsu, Toshihiro Itoh</i>	
High Performance X-Ray Detection Module, with Indium Bumps Interconnections, Manufactured on a Die Level Packaging Line	119
<i>Abdenacer Ait Mani, Patrick Peray, Nadia Miloud-Ali, Andrea Brambilla, Arnaud Peizerat Kim Abdoul-Carime, Loïck Verger</i>	
Fabrication of Flexible Electrochemical Sensor for Interstitial Fluid Biomarker Monitoring Using Pattern Transfer Method	123
<i>Boyu Qin, Jongho Park, Beomjoon Kim</i>	
Investigations into the Use of Synthetic Image Data for the Automated Active Alignment of Micro-Optics	127
<i>Anna-Lena Fritze, Ludger Overmeyer</i>	
Direct Thermal Characterization of Thinned InP-Laser Diodes	129
<i>Kiyoto Taniguchi, Taro Itatani, Joji Maeda, Akihiro Noriki, Takeru Amano</i>	
Deep Learning with De-Embedded S-Parameters for Assessing Crack Propagation in Solder Joints	131
<i>Namgyeong Kim, Minkyu Kang, Hyunwoo Nam, Tae Yeob Kang</i>	
Investigation of Polarization Performance in Polymer Optical Splitters for Co-Packaged Optics	133
<i>Yudai Nagano, Taro Itatani, Fumi Nakamura, Takeru Amano, Joji Maeda, Akihiro Noriki, Satoshi Suda</i>	
3-D Optical Interconnection of Bent Waveguides and Micro-Mirror by Planar Semiconductor Process	135
<i>Keito Kikuchi, Taro Itatani, Yoshinobu Okano, Akihiro Noriki, Takeru Amano</i>	
Non-Destructive Diagnosis of Cracks in SMD Capacitors Using Deep Learning on Impedance Spectra	137
<i>Minkyu Kang, Namgyeong Kim, Hyunwoo Nam, Tae Yeob Kang</i>	
Quantum Dot Doped Polymer Optical Waveguide Amplifier	139
<i>Hayato Kitta, Takaaki Ishigure</i>	
Core Position Accuracy Improvement of Polymer Optical Waveguide Fabricated Using the Mosquito-Method	141
<i>Airi Nakao, Takaaki Ishigure</i>	
Investigation of Surface Activation Conditions Using VUV Light to Enable Room-Temperature Au–Au Bonding	143
<i>Mika Ogino, Kai Takeuchi, Eiji Higurashi</i>	
Multi-Sensor Integrated Urethane Foam Package for Wearable Vital Sensing in Everyday Setting	145
<i>Suguru Sato, Naoto Tomita, Jarred Fastier-Wooller, Shun Muramatsu, Michitaka Yamamoto, Toshihiro Itoh</i>	
Laser-Induced Forward Transfer of Thin Microchips in Quasi-Contact Mode	147
<i>Harindra Kumar Kannoja, Geert Van Steenberge</i>	
Non-Invasive Corrosion Quantification in Electronic Packages Using Smith Charts	151
<i>Tae Yeob Kang, Namgyeong Kim, Minkyu Kang</i>	

Wafer Bonding of Diamond for Improving Heat Dissipation of Properties of Nitride Devices	155
<i>Naoteru Shigekawa, Jianbo Liang, Yutaka Ohno</i>	
Material and Process Characterization to Enable Heavy Copper Wire Bonding on Power Modules	158
<i>Randolph Flauta, Jing Chen, Howie Ding, Rito Wang, Shixing Zhu, Tino Minotti, King Man Tai, Joe Zhou</i>	
<i>Haibin Chen</i>	
Study of Factor Effect on Surge Current Test Performance for Clip-Bonded Semiconductor Devices by Simulation	162
<i>Nick Chenchao Zhong, Thomas Igel-Holtzendorff, Haibo Fan, Tim Böttcher, Owen Yi Kei Law</i>	
40-Channel Detachable Optical Connector Enabling Ultra-High Density Connectivity in Co-Packaged Optics	166
<i>Yuki Fujimaki, Shosuke Ikeda, Kengo Watanabe, Tsunetoshi Saito, Masaki Kotoku</i>	
Single Mode Multifiber Expanded Beam Connector for Immersion Cooling System Using GRIN Lens	170
<i>Alexander William Setiawan Putra, Yusuke Ishibashi, Motohito Takezaki, Kazutaka Aboshi</i>	
Evaluation of Fabricating Polymer Waveguides for Die-to-Die Optical Connections	174
<i>Honoka Shima, Masaharu Kato, Kazunao Yamamoto, Masaki Matsumoto, Yuji Furuta, Hisashi Kaneda</i>	
Development of Planar-Gate Vertical GaN MOSFETs	178
<i>Ryo Tanaka, Tsurugi Kondo, Nao Suganuma, Katsunori Ueno, Shinya Takashima</i>	
EMI Mitigation and Inductance Reduction in SiC Power Modules Through Layout Optimization	182
<i>Raymond Borres, Thiya Warnakulasooriya, Sihoon Choi, Koichi Shigematsu, Masayoshi Yamamoto</i>	
<i>Ang-Ying Lin, Yan Bo Fang, Chien Wei Chang, Po-Kai Chiu, Yan-Cheng Liu</i>	
Research on Low Thermal Resistance/High Reliability Technology for Ultra-Compact Double-Sided Cooled SiC Power Modules	186
<i>Akira Kitamura, Yoshihiro Tateishi, Shoichiro Otani, Satoharu Tanai, Keita Suzuki, Tetsuo Endoh</i>	
<i>Yoshikazu Takahashi</i>	
Additive Fan-Out Packaging for Discrete Components	190
<i>Edsger C. P. Smits, Arjun Wadhwa, Milan Saalmink, Marieke Burghoorn, Iris Kerkhof, Ruben Pranger</i>	
<i>Frans Meeuwsen, Francesca Chiappini, Jeroen van den Brand</i>	